

Appl. No. 10/552,540  
Amdt. Dated February 19, 2008  
Reply to Office Action of November 16, 2007

Attorney Docket No. 81844.0044  
Customer No. 26021

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:  
Shigeru TANAKA, et al.  
Serial No.: 10/552,540  
Confirmation No.: 2300  
Filed: October 11, 2005  
For: THERMOSETTING RESIN  
COMPOSITION, MULTILAYER BODY  
USING SAME, AND CIRCUIT BOARD

Art Unit: 1796  
Examiner: Patrick Dennis  
Niland

**AMENDMENT UNDER 37 C.F.R. § 1.116**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

DO NOT ENTER: /P.N./ 02/26/2008

Dear Sir:

In response to the Final Office Action dated November 16, 2007, due February 16, 2008 (Saturday), please amend the above-referenced application as follows:

**Amendments** to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 27 of this paper.